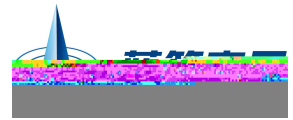
**修订记录**

A	2018-3				
B	2021-2-18	7			



描述

50V~1000V

3.0A SMC

Surface Mount General Purpose Silicon Rectifiers, Reverse Voltage 50 to1000V,Forward Current:3.0A ,SMC thin package.

特征

RoHS 2011/65/EU

Glass Passivated Chip Junction, Lead free in comply with EU RoHS 2011/65/EU directives, For surface mounted applications. Halogen free product.

用途

General purpose.

内部等效电路

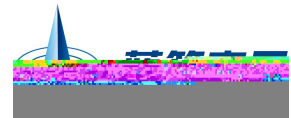


引脚排列



印章代码

See Marking Instructions.



参数 Parameter	符号 Symbol	数值 Rating							单位 Unit
		S3AC	S3BC	S3DC	S3GC	S3JC	S3KC	S3MC	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35							

电参数曲线图

Fig. 1. Forward (a) and Reverse (b) Curing Curves. Fig. 2. Typical Reverse Characteristics

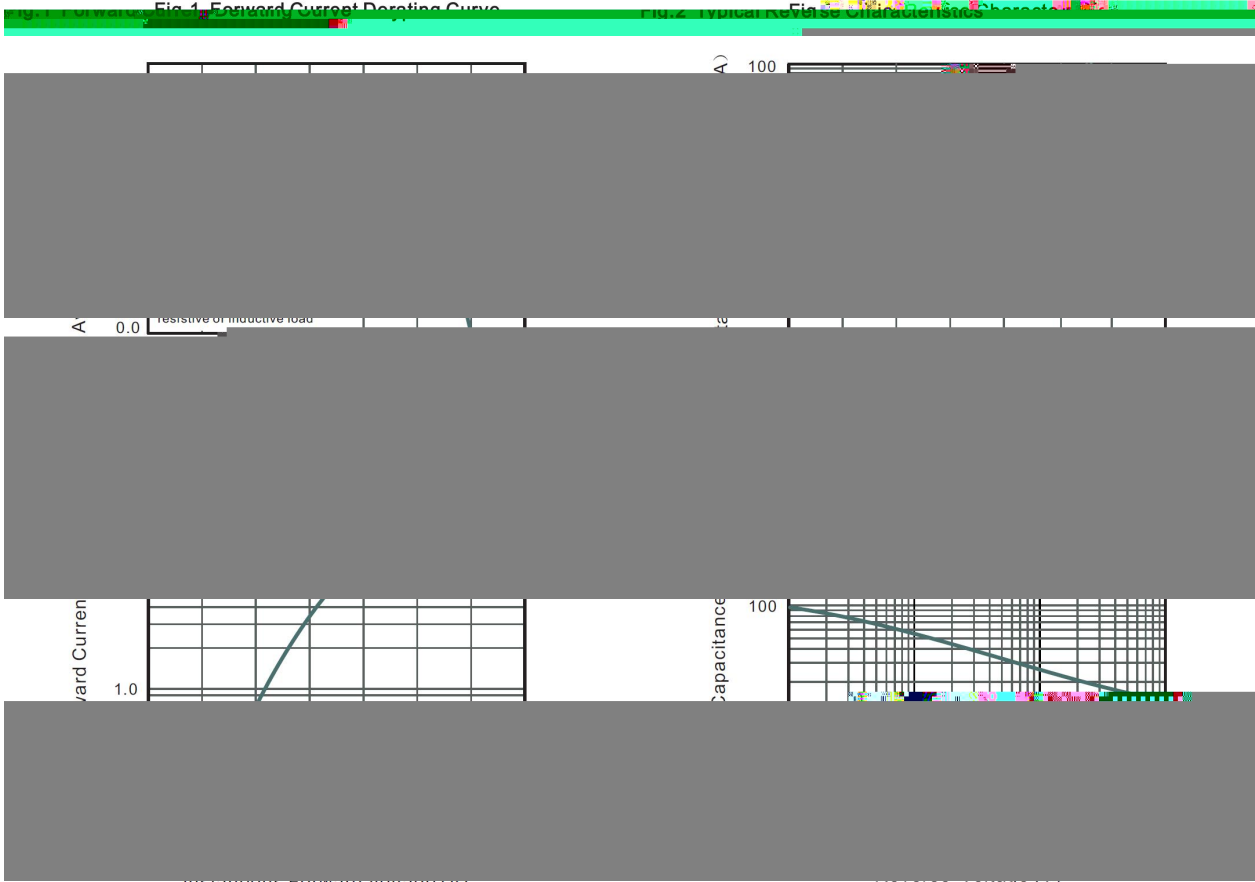
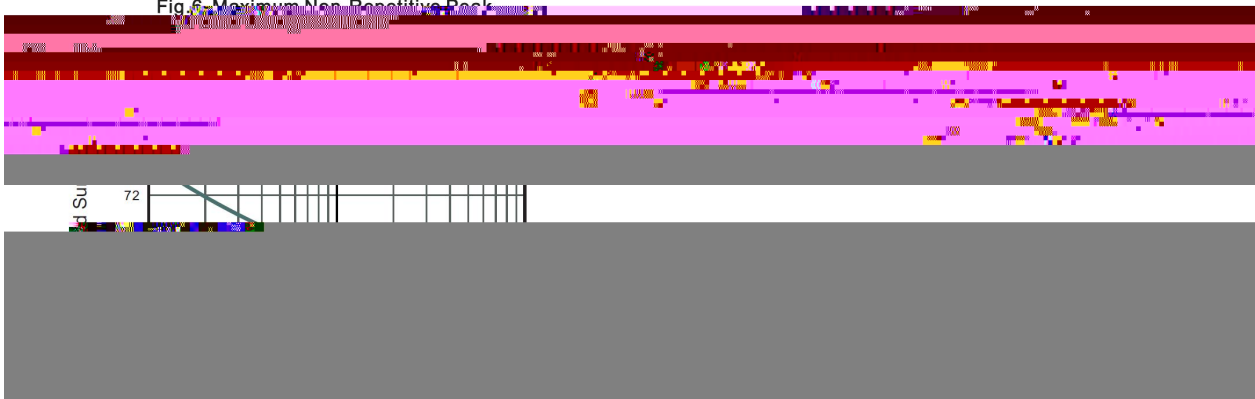
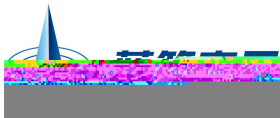


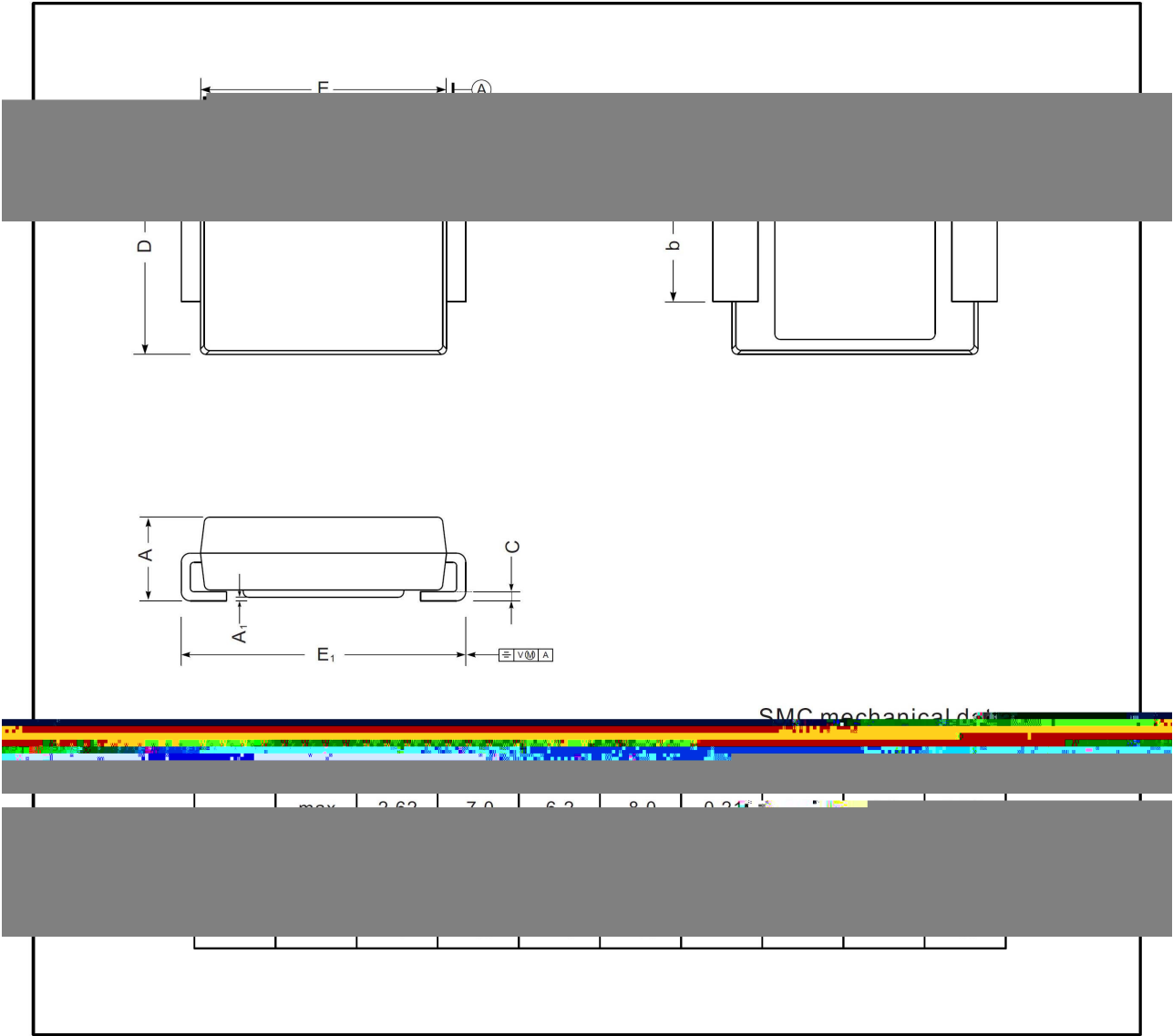
Fig. 6. Maximum Non-Repetitive Pack

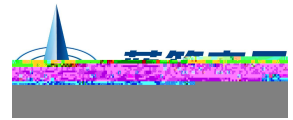




外形尺寸图

SMC

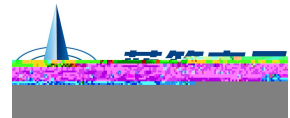




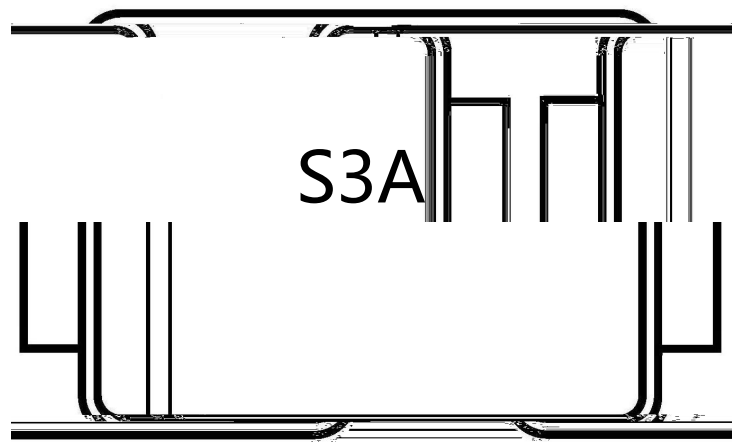
印章说明

Marking





印章说明



说明：

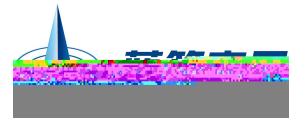
S3A： 为型号代码

： 为生产批号追溯码，第 1 个*为年月代码，后面 3 个*为当月小批号代码

Note:

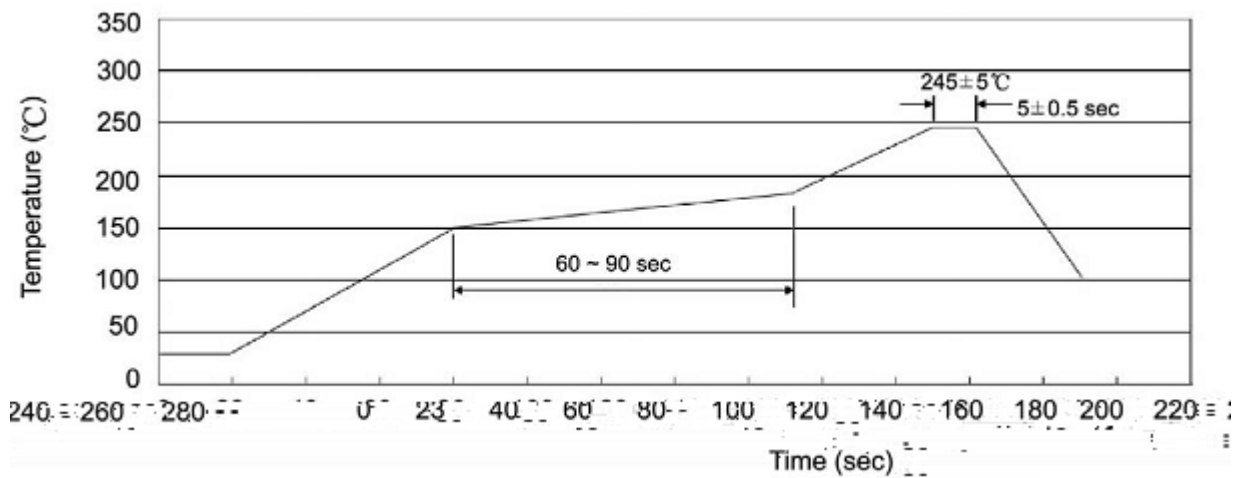
S3A： Product Type Code

： Lot No. Code ,The 1st * means:YM Code ,The last 3 * means:little Lot No Code



Rev.B Feb.-2021

回流焊温度曲线图 无铅 Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|--------|--|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150°C, Time:60~90sec. |
| 2 | 245±5 | | 5±0.5sec; | | 2.Peak Temp.:245±5°C, Duration:5±0.5sec. |
| 3 | | 2 | 10°C/sec. | | 3. Cooling Speed: 2~10°C/sec. |

耐焊接热试验条件

260±5°C 10±1 sec. Temp.:260±5°C Time:10±1 sec

包装规格

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SMC	3000	2	6000	6	36000	13" ×16	337X337X49	380X335X366

使用说明